HEAT SINK COMPOUND

For Thermal coupling and heat dissipation

1. GENERAL DESCRIPTION

Compound to increase the thermal conductivity and the efficient heat dissipation at electronic components.

2. FEATURES

- High thermal conductivity.
- Excellent moisture buffer.
- Low metallic impurity content.

3. APPLICATIONS

- Printed circuit boards.
- Electronic components.
- Control assemblies.

4. DIRECTIONS

- Apply to a clean, dry surface.
- Do not mix with other products.
- Do not use on energized equipment.

A safety data sheet (SDS) according to EC Regulation N° 1907/2006 Art.31 and amendments is available for all products.

5. TYPICAL PRODUCT DATA

Appearance : Paste.
Color : White.
Odor : Characteristic odor.
Density @ 20°C : 2.3 g/cm3
Operating temperature : -50°C to 300 °C

6. PACKAGING

Tube: 20G
100G

All statements in this publication are based on service experience and/or laboratory testing. Because of the wide variety of equipment and conditions and the unpredictable human factors involved, we recommend that our products be tested on-the-job prior to use. All information is given in good faith but without warranty neither expressed nor implied.
This Technical Data Sheet may already have been revised at this moment for reason such as legislation, availability of components and newly acquired experiences. The latest and only valid version of this Technical Data Sheet will be sent to you upon simple request or can be found on our website: www.crcind.com.
We recommend you to register on this website for this product so you will be able to receive any future updated version automatically.

Version : 4.1
Date: 6 November 2021